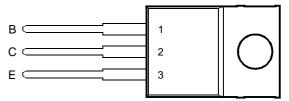
- Designed for Complementary Use with the TIP30 Series
- 30 W at 25°C Case Temperature
- 1 A Continuous Collector Current
- 3 A Peak Collector Current
- Customer-Specified Selections Available

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT	
	TIP29		80		
Collector-base voltage (I _F = 0)	TIP29A	\/	100	V	
Collector-base voltage (IE = 0)	TIP29B	V _{CBO}	120	V	
	TIP29C		140		
	TIP29		40		
Collector emitter voltage (L = 0)	TIP29A		60	V	
Collector-emitter voltage (I _B = 0)	TIP29B	V _{CEO}	80	V	
	TIP29C		100		
Emitter-base voltage			5	V	
Continuous collector current			1	Α	
Peak collector current (see Note 1)			3	Α	
Continuous base current			0.4	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			30	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			2	W	
Unclamped inductive load energy (see Note 4)			32	mJ	
Operating junction temperature range			-65 to +150	°C	
Storage temperature range			-65 to +150	°C	
Lead temperature 3.2 mm from case for 10 seconds			T _L 250		

NOTES: 1. This value applies for $t_p \le 0.3$ ms, duty cycle $\le 10\%$.

- 2. Derate linearly to 150°C case temperature at the rate of 0.24 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = 0.4 A, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_S = 0.1 Ω , V_{CC} = 20 V.



TIP29, TIP29A, TIP29B, TIP29C NPN SILICON POWER TRANSISTORS

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electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
	Collector-emitter breakdown voltage	I _C = 30 mA		TIP29 TIP29A	40 60			
V _{(BR)CEO}			$I_C = 30 \text{ mA}$ $I_B = 0$ (see Note 5)	TIP29B	80			V
		,		TIP29C	100			
	V _{CE} = 80 V	V _{CE} = 80 V	V _{BE} = 0	TIP29			0.2	mA
1	Collector-emitter	V _{CE} = 100 V	$V_{BE} = 0$	TIP29A			0.2	
I _{CES}	cut-off current	V _{CE} = 120 V	$V_{BE} = 0$	TIP29B			0.2	ША
		V _{CE} = 140 V	$V_{BE} = 0$	TIP29C			0.2	
loso	Collector cut-off	V _{CE} = 30 V	I _B = 0	TIP29/29A			0.3	0.3 mA
I _{CEO}	current	$V_{CE} = 60 V$	$I_B = 0$	TIP29B/29C			0.3	ША
I _{EBO}	Emitter cut-off	V _{EB} = 5 V	I _C = 0				1	mA
EBO	current							110 (
h _{FE}	Forward current	$V_{CE} = 4 V$	$I_C = 0.2 A$	(see Notes 5 and 6)	40			
	transfer ratio	V _{CE} = 4 V	I _C = 1 A		15		75	
V _{CE(sat)}	Collector-emitter	I _B = 125 mA	I _C = 1 A	(see Notes 5 and 6)			0.7	V
· CE(Sat)	saturation voltage						• • • • • • • • • • • • • • • • • • • •	
V _{BE}	Base-emitter	V _{CE} = 4 V	$I_C = 1 A$	(see Notes 5 and 6)			1.3	V
DL.	voltage	· CE		(
h _{fe}	Small signal forward	$I \lor C = 10 \lor$	$I_{\rm C} = 0.2 {\rm A}$	f = 1 kHz	20			
ie .	current transfer ratio	GL 101		· -				
h _{fe}	Small signal forward	V _{CE} = 10 V	$I_{C} = 0.2 \text{ A}$	f = 1 MHz	3			
. 101	current transfer ratio							

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			4.17	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

		PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
Ī	t _{on}	Turn-on time	I _C = 1 A	$I_{B(on)} = 0.1 A$	$I_{B(off)} = -0.1 A$		0.5		μs
Ī	t _{off}	Turn-off time	$V_{BE(off)} = -4.3 \text{ V}$	$R_L = 30 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		2		μs

 $^{^{\}dagger} \ \ \mbox{Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.}$

^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN VS COLLECTOR CURRENT $T_{CS631AD}$ $T_{C} = 25^{\circ}C$ $T_{C} = 25^{\circ}C$ $T_{C} = 300 \,\mu s, \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$ $T_{C} = 1000 \, duty \, cycle < 2\%$

COLLECTOR-EMITTER SATURATION VOLTAGE

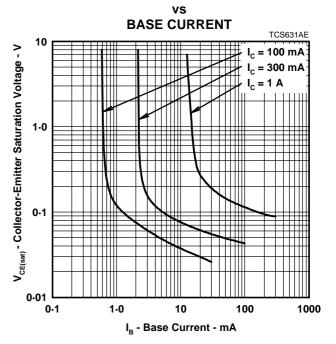
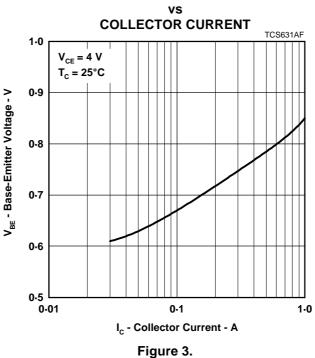


Figure 2.

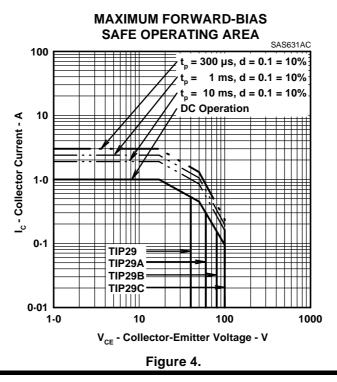
Figure 1.

BASE-EMITTER VOLTAGE



Power

MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION

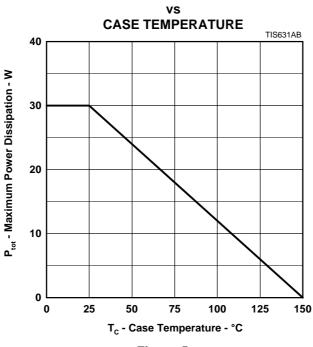


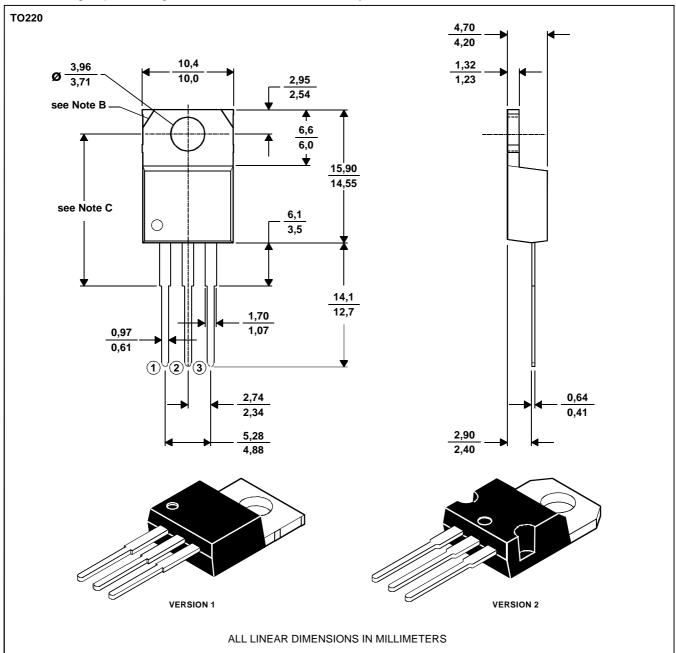
Figure 5.

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.
C. Typical fixing hole centre stand off height according to package version.
Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE



TIP29, TIP29A, TIP29B, TIP29C NPN SILICON POWER TRANSISTORS

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